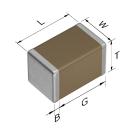


积层贴片陶瓷片式电容器

C2012X7T2V153M085AA

RoHS Reach Halogen Free Pb Free

交货型号	C2012X7T2V153MT****
用途	一般等级
特点	Mid 中耐压(100~630V)
系列	C2012 [EIA 0805]
状态	▲ 量产体制(新设计非推荐)



尺寸		
长度(L)	2.00mm ±0.20mm	
宽度(W)	1. 25mm ± 0.20 mm	
厚度(T)	$0.85 \text{mm} \pm 0.15 \text{mm}$	
端子宽度(B)	0. 20mm Min.	
端子间隔(G)	0.50mm Min.	
推荐焊盘布局(PA)	1.00mm to 1.30mm(Flow Soldering)	
1世存/杆益41/四 (FA)	0.90mm to 1.20mm(Reflow Soldering)	
推荐焊盘布局(PB)	1.00mm to 1.20mm(Flow Soldering)	
]比针/产血/II/回 (t D)	0.70mm to 0.90mm(Reflow Soldering)	
推荐焊盘布局(PC)	0.80mm to 1.10mm(Flow Soldering)	
1世代が年前41/四はし/	0.90mm to 1.20mm(Reflow Soldering)	

电气特性		
电容	15nF ±20%	
额定电压	350VDC	
温度特性	X7T (+22, -33%)	
耗散因数(Max.)	2.5%	
绝缘电阻 (Min.)	10000M Ω	

	其他	
M1+0>	流体	
焊接方法	回流	
AEC-Q200	NO NO	
包装形式	纸编带 (180mm卷筒)	
包装个数	4000pcs	

[!] Images are for reference only and show exemplary products.

[!] This PDF document was created based on the data listed on the TDK Corporation website.

[!] All specifications are subject to change without notice.

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特性图表(这是参考数据,并不保证产品的特性。)

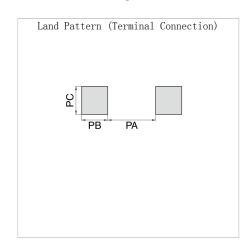
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Associated Images



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